

CLAIMS

1. A conductive adhesive comprising a conductive filler and a binder resin as main components, wherein a content of the conductive filler is in a range from 20 wt% to 70 wt%.
2. The conductive adhesive according to claim 1, wherein the conductive filler comprises a metal filler having protrusions.
3. The conductive adhesive according to claim 2, wherein the conductive filler having protrusions is a dendrite filler.
4. The conductive adhesive according to claim 1, wherein the conductive filler is a mixture of 30-99 wt% of a filler having protrusions and 1-70 wt% of at least one filler having a shape selected from the group consisting of a scale, a flake and a particle.
5. The conductive adhesive according to claim 1, wherein the content of the conductive filler is in a range from 30 wt% to 50 wt%.
6. The conductive adhesive according to claim 1, wherein the conductive filler is at least one metal selected from the group consisting of copper, silver, gold, platinum, palladium, nickel, stainless steel and an alloy thereof.
7. The conductive adhesive according to claim 1, wherein the conductive filler is prepared by coating a metal with at least one substance selected from the group consisting of silver, gold, palladium, silica and resin.
8. The conductive adhesive according to claim 1, wherein the conductive filler has an average particle diameter ranging from 1 μm to 100 μm .
9. The conductive adhesive according to claim 1, wherein the binder resin is an elastic adhesive resin.
10. A package of an electronic element provided by electrically connecting a circuit substrate electrode to an electronic element electrode by means of a conductive adhesive containing a conductive filler and a binder resin, wherein an average content of the conductive filler is in a range from 20 wt% to

70 wt%,

the conductive filler comprises a metal filler having protrusions,
the content of the conductive filler is higher than the average content for the adhesive present in a gap between the electrodes, and the content of the conductive filler becomes lower than the average content for the adhesive squeezed out of the gap.

11. The package of an electronic element according to claim 10, wherein the conductive filler comprises a metal filler having protrusions.
12. The package of an electronic element according to claim 11, wherein the conductive filler having protrusions is a dendrite filler.
13. The package of an electronic element according to claim 10, wherein the conductive filler is a mixture of 30-99 wt% of a filler having protrusions and 1-70 wt% of at least one filler having a shape selected from the group consisting of a scale, a flake and a particle.
14. The package of an electronic element according to claim 10, wherein the content of the conductive filler is in a range from 30 wt% to 50 wt%.
15. The package of an electronic element according to claim 10, wherein the conductive filler is at least one metal selected from the group consisting of copper, silver, gold, platinum, palladium, nickel, stainless steel and an alloy thereof.
16. The package of an electronic element according to claim 10, wherein the conductive filler is prepared by coating a metal with at least one substance selected from the group consisting of silver, gold, palladium, silica and resin.
17. The package of an electronic element according to claim 10, wherein the conductive filler has an average particle diameter ranging from 1 μm to 100 μm .
18. The package of an electronic element according to claim 10, wherein the binder resin is an elastic adhesive resin.
19. The package of an electronic element according to claim 10, wherein

the content of the conductive filler is in a range from 75 wt% to 95 wt% for the adhesive in a gap between the circuit substrate electrode and the electronic element electrode.

20. The package of an electronic element according to claim 11, wherein the circuit substrate electrode and the electronic element electrode are connected to each other by being scratched partially on the surfaces by the metal filler having protrusions.

21. The package of an electronic element according to claim 10, wherein the spacing between the element electrode and the substrate electrode is at least 1.1 times a minimum dimension (D min) of a smallest conductive filler contained in the conductive resin, and at most 20 times a maximum dimension (D max) of a biggest conductive filler contained in the conductive resin.

22. A packaging method comprising connecting electrically a circuit substrate electrode to an electronic element electrode by means of a conductive adhesive comprising a conductive filler and a binder resin, wherein an average content of the conductive filler is in a range from 20 wt% to 70 wt% and the circuit substrate is connected to the electronic element electrode by:

applying the adhesive to a gap between the circuit substrate electrode and the electronic element electrode;

applying the circuit substrate electrode and the electronic element electrode with pressure ranging from 0.01 MPa to 50 MPa; and

squeezing out the adhesive from the gap between the electrodes so that the adhesive remaining in the gap contains the conductive filler with a higher content than the average content.

23. The packaging method according to claim 22, wherein the conductive filler comprises a metal filler having protrusions.

24. The packaging method according to claim 23, wherein the conductive filler having protrusions is a dendrite filler.

25. The packaging method according to claim 22, wherein the conductive filler is a mixture of 30-99 wt% of a filler having protrusions and 1-70 wt% of

at least one filler having a shape selected from the group consisting of a scale, a flake and a particle.

26. The packaging method according to claim 22, wherein the content of the conductive filler is in a range from 30 wt% to 50 wt%.

27. The packaging method according to claim 22, wherein the conductive filler is at least one metal selected from the group consisting of copper, silver, gold, platinum, palladium, nickel, stainless steel and an alloy thereof.

28. The packaging method according to claim 22, wherein the conductive filler is prepared by coating a metal with at least one substance selected from the group consisting of silver, gold, palladium, silica and resin.

29. The packaging method according to claim 22, wherein the conductive filler has an average particle diameter ranging from 1 μm to 100 μm .

30. The packaging method according to claim 22, wherein the binder resin is an elastic adhesive resin.

31. The packaging method according to claim 22, wherein the content of the conductive filler is in a range from 75 wt% to 95 wt% for the adhesive in a gap between the circuit substrate electrode and the electronic element electrode.

32. The packaging method according to claim 23, wherein the circuit substrate electrode and the electronic element electrode are connected to each other by being scratched partially on the surfaces by the metal filler having protrusions.

33. The packaging method according to claim 22, wherein the spacing between the element electrode and the substrate electrode is at least 1.1 times a minimum dimension (D min) of a smallest conductive filler contained in the conductive resin, and at most 20 times a maximum dimension (D max) of a biggest conductive filler contained in the conductive resin.